
Preskusne metode za električne materiale, tiskana vezja ter druge povezovalne strukture in sestave - 3-719. del: Preskusne metode za povezovalne strukture (tiskana vezja) - Nadzorovanje spreminjanja upornosti enojno pokovinjenih lukenj med toplotnimi cikli

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-719: Test methods for interconnection structures (printed boards) - Monitoring of single plated-through hole (PTH) resistance change during thermal cycling

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Méthodes d'essai pour les matériaux électriques, les cartes imprimées et les autres structures et assemblages d'interconnexion - Partie 3-719: Méthodes d'essai pour les structures d'interconnexion (cartes imprimées) - Contrôles de la variation de résistance des trous métallisés uniques (PTH) au cours des cycles thermiques

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ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD
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Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 3-719: Test methods for interconnection structures (printed boards) - Monitoring of single plated-through hole (PTH) resistance change during temperature cycling (IEC 61189-3-719:2016)

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Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 3-719: Prüfverfahren für Verbindungsstrukturen (Leiterplatten) - Überwachung des Widerstands von Einzeldurchkontaktierungen (PTH - plated-through hole) bei Temperaturwechselbeanspruchung (IEC 61189-3-719:2016)

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Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61189-3-719:2016**European foreword**

The text of document 91/1303/FDIS, future edition 1 of IEC 61189-3-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-3-719:2016.

The following dates are fixed:

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-2-14	-	Environmental testing -- Part 2-14: Tests - Test N: Change of temperature	EN 60068-2-14	-
IEC 60068-2-58	2015	Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)	EN 60068-2-58	2015
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IPC-2221	-	Generic Standard on Printed Board Design -		-

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INTERNATIONAL STANDARD

NORME INTERNATIONALE

**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 3-719: Test methods for interconnection structures (printed boards) –
Monitoring of single plated-through hole (PTH) resistance change during
temperature cycling**

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structures d'interconnexion et ensembles –
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uniques (PTH) au cours des cycles de températures**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 3-719: Test methods for interconnection structures
(printed boards) – Monitoring of single plated-through hole (PTH)
resistance change during temperature cycling**

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International Standard IEC 61189-3-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1303/FDIS	91/1327/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.